

Abstract of Disclosure

A LED package structure includes a substrate, a light emitting diode die located on the substrate, and a phosphoric medium layer
5 located on the substrate and covered the light emitting diode die.
The phosphoric medium layer has a package mold precipitated a phosphor sediment layer on bottom and the phosphor sediment layer tightly covers the light emitting diode die to reduce the light-color leakage rate of the LED.

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